



Fiscal year end financial result Explanatory meeting

Annual report of 2008 year

2009. March 25

YAC Co., Ltd.

**(Ticker Symbol:6298)
<http://www.yac.co.jp>**



Agenda

- 1. Greeting and company outline :**
President and Chief Executive Officer : Takefumi Momose
- 2. Fiscal year end financial result outline :**
Management Headquarters accounting Manager : Hiroshi Furuhashi
- 3. The planning of year 2009 :**
(The 10th medium term of planning outline)
President and Chief Executive Officer : Takefumi Momose
- 4. Question and answers :**



Essential message of a day

- **Constructing high earnings of corporate culture and aim expand business.
(The 10th medium term of planning)**
 - **Reinforce for business structure.**
 - **Challenge for more growing.**

- **Participate the solar battery business.**



1. Company Outline



1-1. Basic information

(Day of 2009.May.25)

Company Name	Y. A. C. Co., Ltd.
Ticker Symbol	6298 (1st-sec. /TSE, Japan)
Establishment	1973. May
C . E . O .	Takefumi Momose
F a c i l i t i e s	Head Quarters: Akishima-Tokyo Sales Offices: Osaka, Oita, Akishima Tokyo Hsinchu-Taiwan, Shanghai-China Factories: Akishima-Tokyo, Yamanashi, Kumamoto, Ohita
Affiliated Companies	YAC Niigata Seiki Co., Ltd. (Niigata, Japan) HYAC Corporation (CA, USA) YAC Systems Singapore Pte Ltd (Singapore)
Investing company	ND Materials Co., Ltd. Shinoda plasma Co., Ltd.
Paid-in Capital	¥2,756M
Business Areas	R&D, Manufacturing & Sales of industrial electronics related equipments & industrial cleaning related equipments.
Financial Year	From April 1 to March 31



1-2. Major Products

Hard Disk Equipment Area

- Burnisher
- Wiping System
- Clean Conveyor

LCD Equipment Area

- Plasma Dry Etching System
- Plasma Dry Ashing System
- Anneal System

Semiconductor Equipment Area

- Test Handler for Logic IC's

Cleaning Equipment Area

- Automatic Bagging Machine
- Shirts Pressing Machine
- Apparel Machine

FEL Equipment Area

- Emitter for FEL

Solar battery Equipment Area

- Texturing System
- Spread chamber
- ISO/PSG system
- AR coating
- Syringe system



Major Products

< Hard Disk Equipment Area >

Burnisher	The disk surface precise polishing equipment to eliminate the nano-size projections on the disk surface after the process of magnetic film generating.
Wiping System	The equipment to remove particles on the disk surface and to equalize the lubricant agent after the process of magnetic film generating.
Clean Conveyor (for Hard Disk Factories)	The roller type clean conveyer system <ul style="list-style-type: none"> - Easier line designing by module concept - Higher transport efficiency than AGV or OHT by free loading and unloading as-needed.
Clean Conveyor (for Semiconductor , Solar cell Factories)	The roller type clean conveyer system <ul style="list-style-type: none"> - Larger width and higher load bearing & transporting speed are required. - Semiconductor: for 300mm wafer cassette transporting, - Solar cell :for Glass Substrate or 5inch wafer cassette transporting.
Clean Conveyor (for LCD Factories)	The roller type clean conveyer system <ul style="list-style-type: none"> - Larger width and higher load bearing & transporting speed are required for transporting Glass. substrate cutting by panel size.



Burnisher



**Clean Conveyor
(for Hard Disk Factories)**



**Clean Conveyor
(for Semiconductor Factories)**

< LCD Equipment Area >

Plasma Dry Etching System

The equipment to generate the micro transistors which control the directions of liquid crystals in each cell.
 After eliminating of the area except hardened area by exposure, this equipment eliminates the exposed thin film by using plasma.



Applicable Glass Substrate Sizes

- G2
- G4
- G4.5
- G5
- G5.5
- G6
- G7
- G7.5
- G8

**G7 Plasma Dry Etching System
 (3-chamber type)**



Major Products

< Semiconductor Equipment Area >

**IC Test Handler
(For Logic ICs)**

The equipment to make automatic sorting based on the test result signal from the tester in the IC testing process.
It also makes high or low temperature testing environment (-55 deg.C to 155 deg.C) as the occasion demands.



**IC Test Handler
(4-IC Parallel Testing, Ambient Type)**



**=New Model= IC Test Handler
(16-IC Parallel Testing)**



Major Products

< Cleaning Equipment Area >

Shirt Pressing Machines (For Body)	The machine to press the body area of the shirt on the the dummy body by shutting in between 2 heat plates. (Options) Dual-Body Type, Single Body Type Auto Carry System. (The system to make automatic transferring to the hanger after finishing)
Pressing Machines (For Tuck & Sleeve)	The machine to press tuck & sleeve areas (Options) Dual type, Single Type.
Pressing Machines (For Collar & Cuffs)	The machine to press Collar & Cuffs areas (Options) Dual type, Single Type.
Bagging Machines	The machine to bag the finished items using plastic film cover. (Options) Hanger Type, Folder Type.
Apparel related Machines	Sponging Machine: to steam and press clothes for stability, Fusing Machine: to fuse clothes after cutting by parts, Pressing Machine: to press for smoothing down wrinkles.



**Shirt Pressing Machine
(For Body: Dual Type)**



**Bagging Machine
(Hanger Type)**



**Sponging Machine
(For Apparel)**



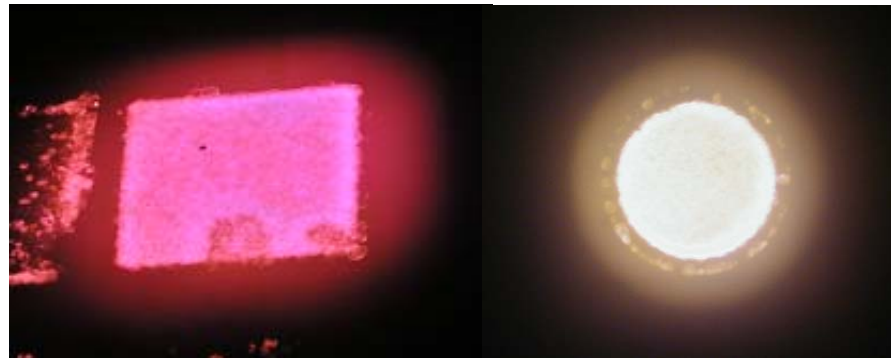
**Pressing Machine
(For Apparel)**



Major Products

< FEL Equipment Area >

Manufacturing of Nano-Diamond Thin Film	The Electron Emitter using Nano-Diamond thin film for FEL (Field Emission Lamp) Feature: (Lamp use for Nano-diamond thin film.) <ul style="list-style-type: none">• Different as previous fluoresce light, non toxic substance like mercury / lead.• Very high energy and environmentally efficiency compare with a LED lamp.• Long-Life cycle Lamp compare with fluoresce light.• Less generate heat compare with fluoresce light and LED.• Flexible control of light wave length and color mixture.
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radiation



Major Products

< Solar battery Equipment Area >

Solar battery (Monocrystal / Polycrystalline) process equipment.

Monocrystal and Polycrystalline type solar battery hole line (in-line batch processing) product.

Feature:

- Texturing (batch in-line equipment)
- Spread chamber (P coating equipment / tube (batch) type / in-line equipment)
- PSG (ISO) (batch in-line equipment)
- Prevent reflex coat (AR) sputtering (PECVD equipment)
- Wire printing (Screen print / Dry chamber)
- Layer wire (BSF form) (Burning chamber)
- Other related equipments





2. Terminal financial result



2-1 Highlight of financial Result (Consolidated)

(Million¥)

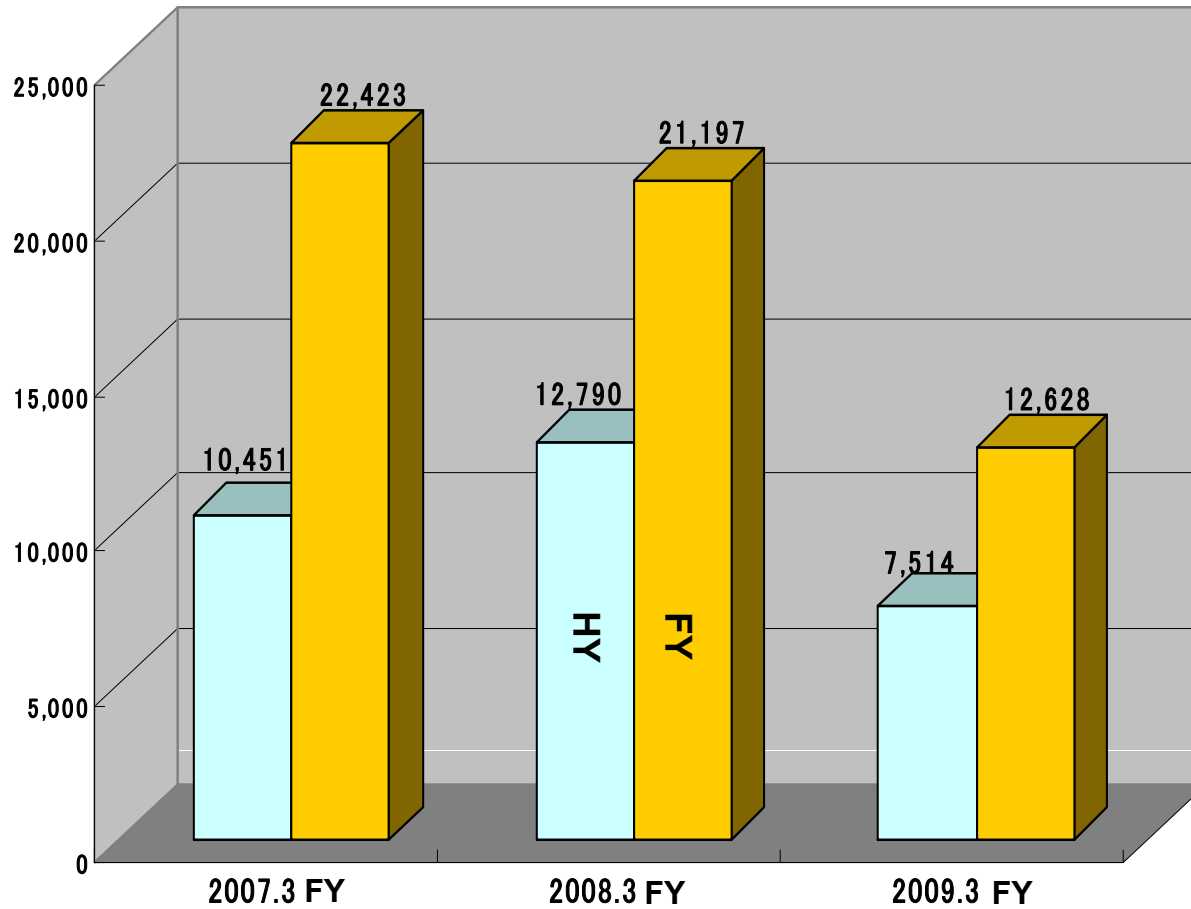
Items	2007March(actual)	2008March(actual)	2009March	terminal Change from last year	terminal Change from last year(%)
	FY	FY	FY		
Net Sales	22,423	21,197	12,628	▲8,569	▲40.4%
Memory Disk	9,899	7,039	2,238	▲4,801	▲68.2%
Plasma system	9,400	10,919	7,609	▲3,310	▲30.3%
Semiconductor	1,403	1,093	1,164	71	6.5%
Cleaning System	1,720	2,145	1,615	▲530	▲24.7%
FEL	—	—	1	—	—
Operating Income	3,676	2,295	255	▲2,040	▲88.9%
Ordinary income	3,583	2,371	430	▲1,941	▲81.9%
Net income	2,103	1,524	510	▲1,014	▲66.5%
Earning /Share	219.1	158.1	54.8	▲103.3	▲65.3%
Operating income Ratio	16.4%	10.8%	2.0%	—	—
R & D expenses	236	287	310	23	8.0%
Capital expenditure	98	213	217	▲104	▲32.4%
Depreciation	159	148	183	35	23.6%



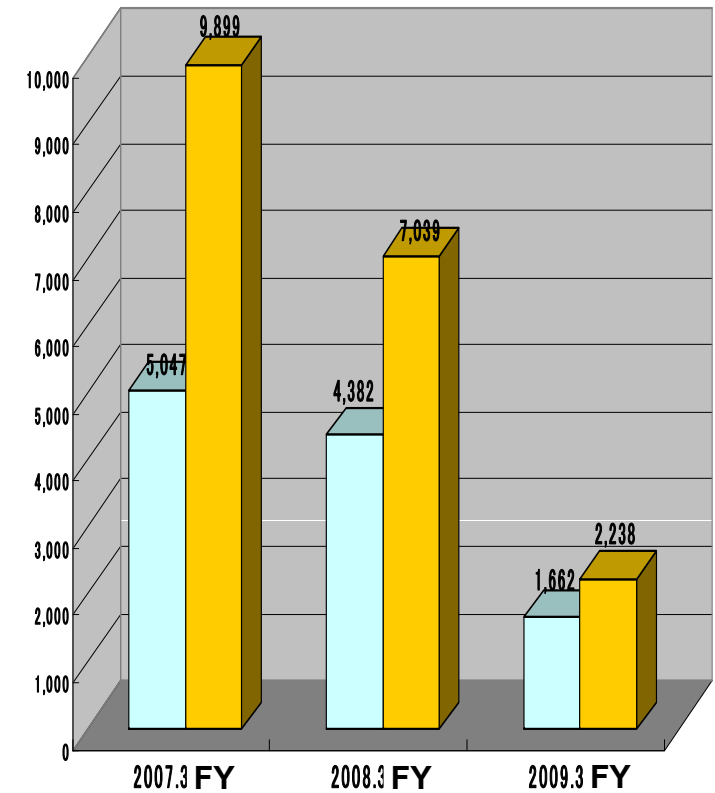
2-2 Sales by Business Unit (Consolidated)

(Million¥)

Total Sales



Memory Disk Sales

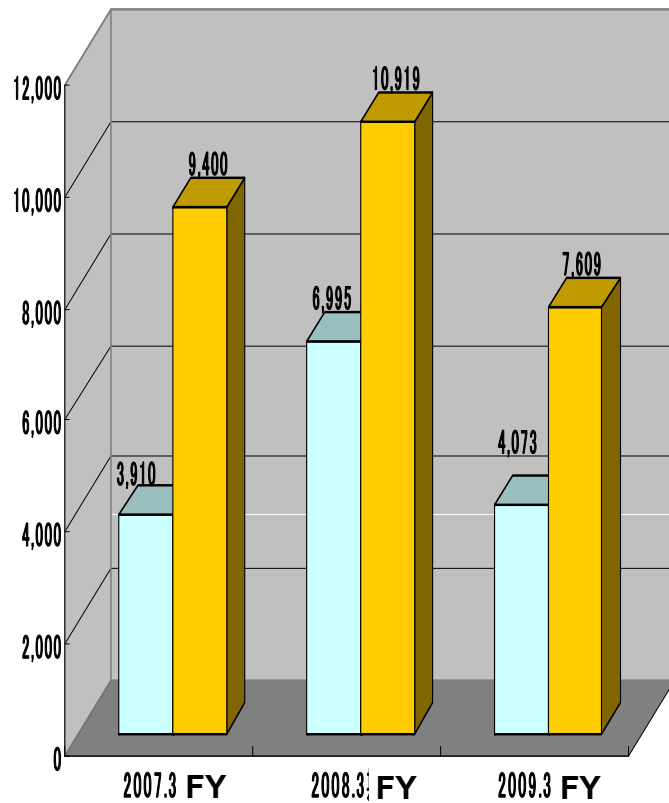




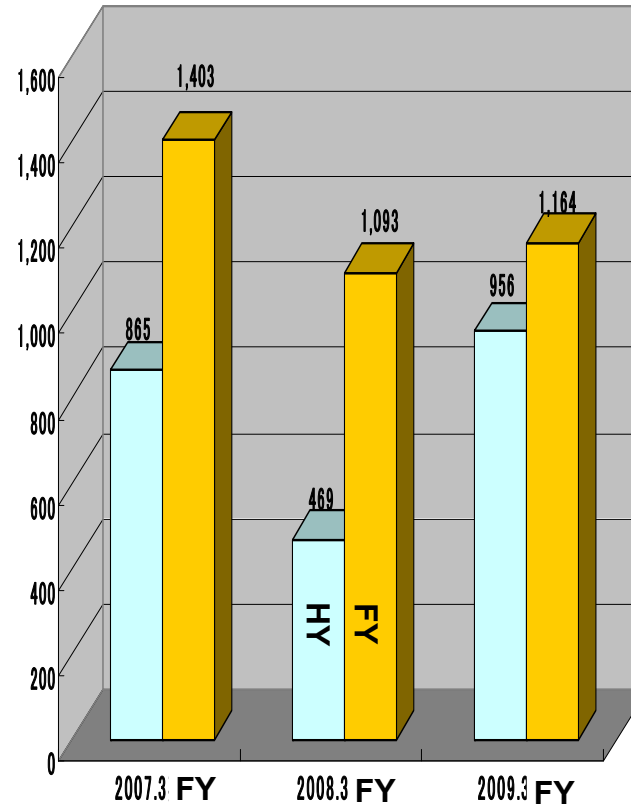
2-2 Sales by Business Unit (Consolidated)

(Million¥)

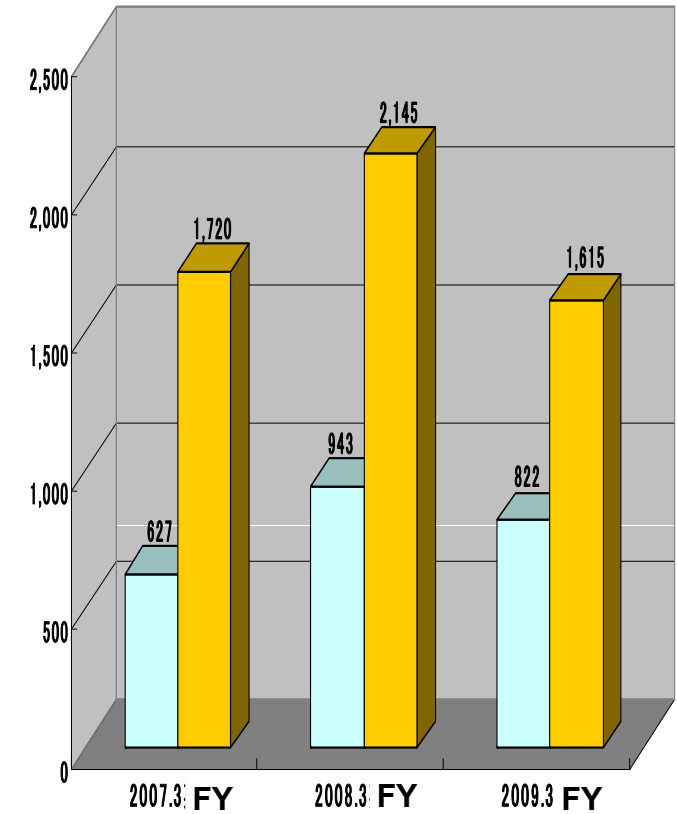
Plasma System



Semiconductor



Cleaning System





2-3 Amount of Received Orders by Business Unit (Consolidated) (Million¥)

Business Units	2007 FY	2008 FY	2009 FY	Terminal Change from last year	Terminal Change from last year(%)
Memory Disk	9,582	5,105	1,667	▲3,438	▲67.3%
Plasma System	10,872	9,969	5,778	▲4,191	▲42.0%
Semiconductor	1,367	1,337	773	▲564	▲42.2%
FEL	—	—	1	—	—
Total	21,822	16,412	8,220	▲8,192	▲49.9%

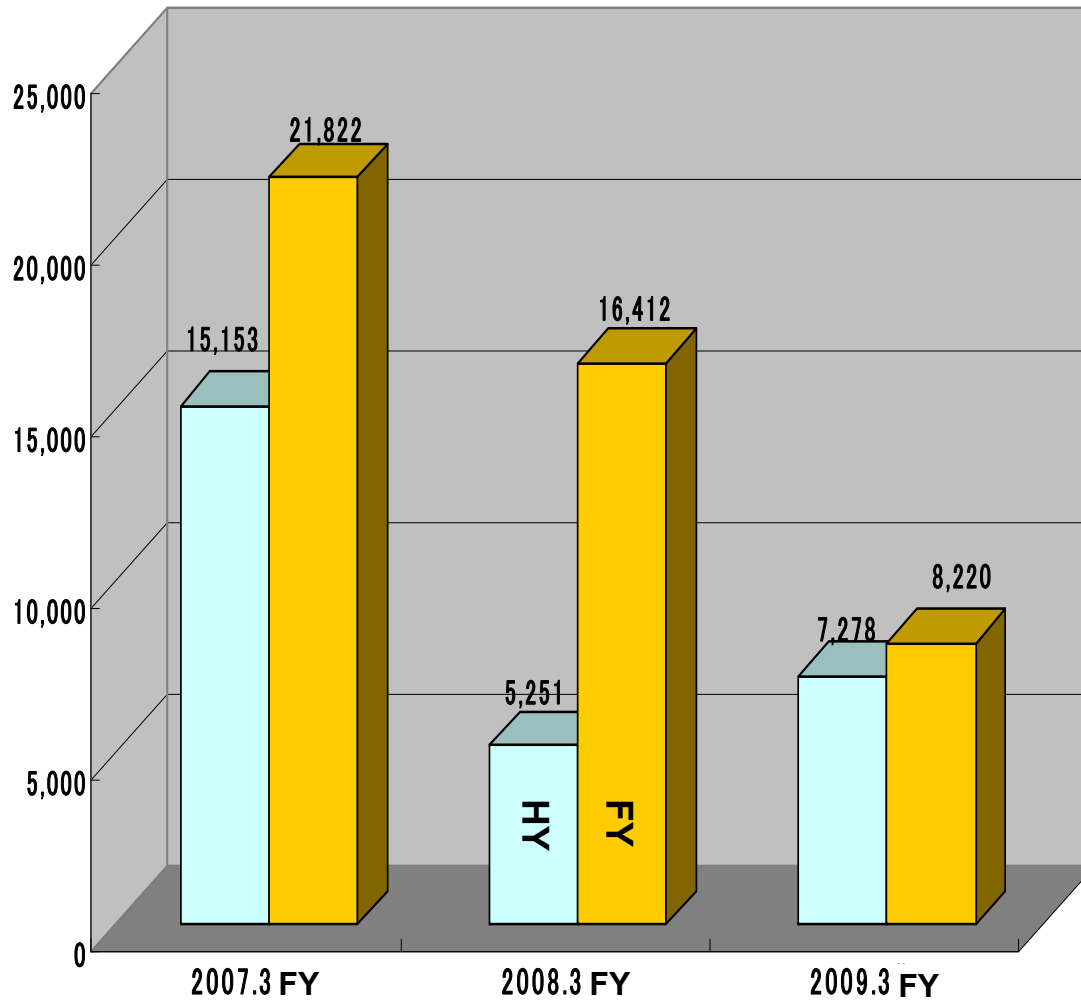
Note) Amounts of Received Order on Cleaning Related Segment is the same amounts as the amounts of Sales because that is carried on the planed production based on the sales plan.



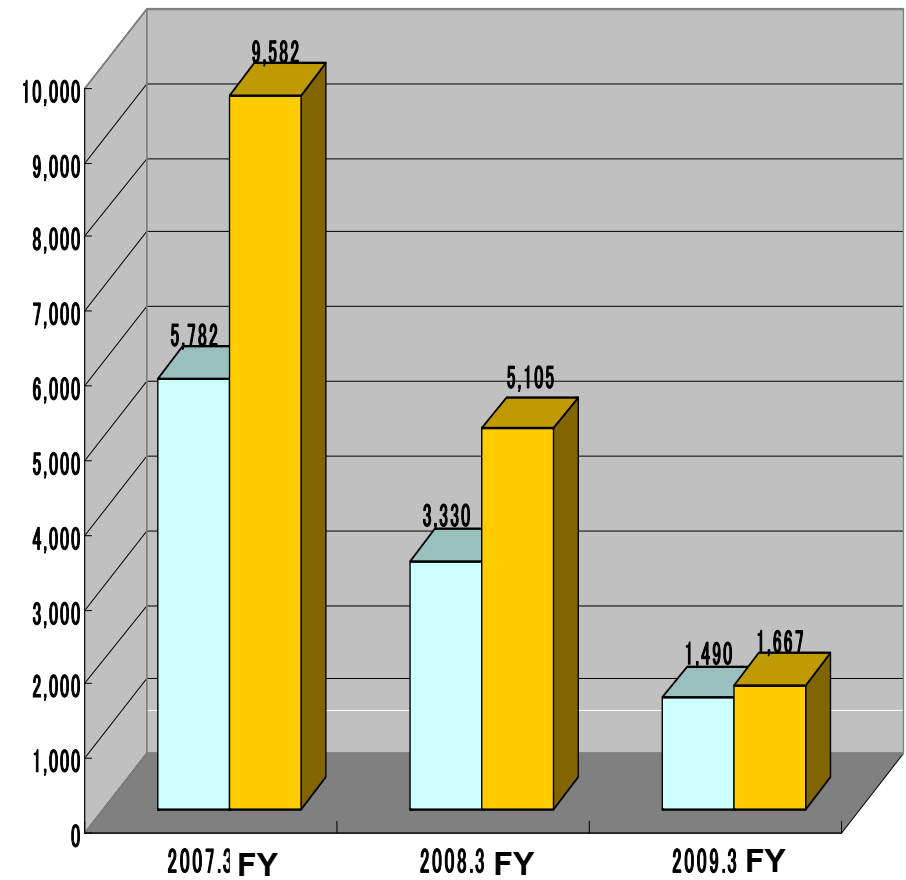
2-3 Amount of Received Orders by Unit (Consolidated)

(Million¥)

Total Orders



Memory Disk Orders

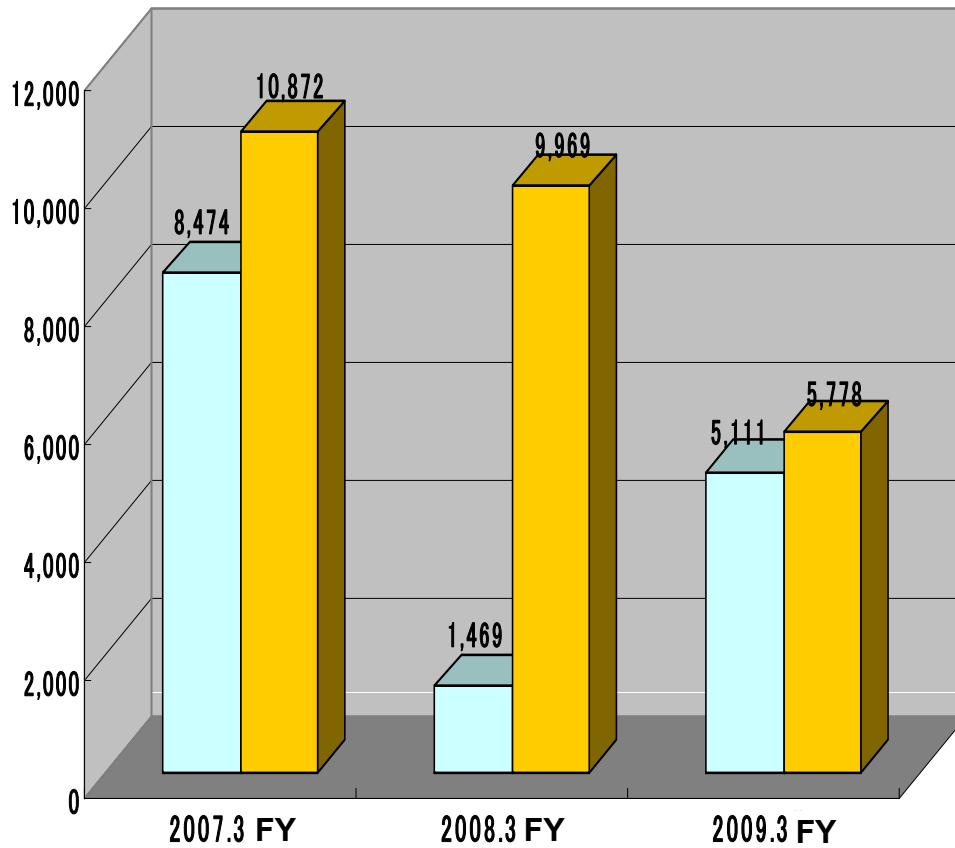




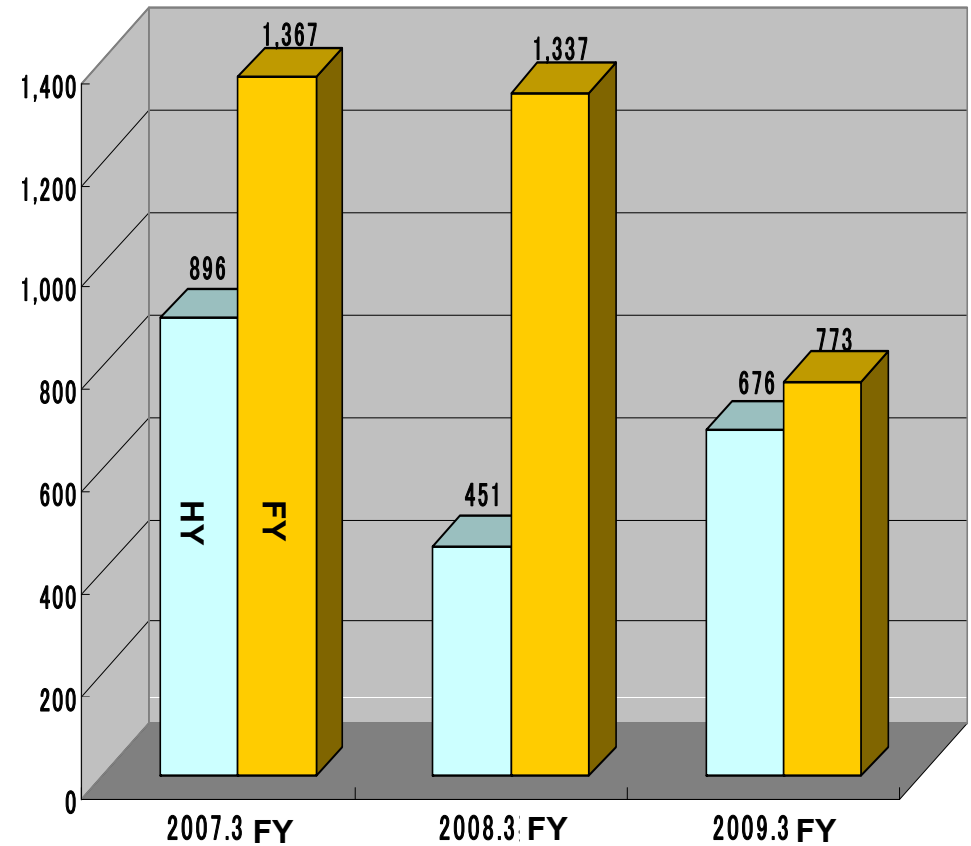
2-3 Amount of Received Orders by Unit (Consolidated)

(Million¥)

Plasma System



Semiconductor





2-4 Backlog Orders by Business Unit (Consolidated)

(Million¥)

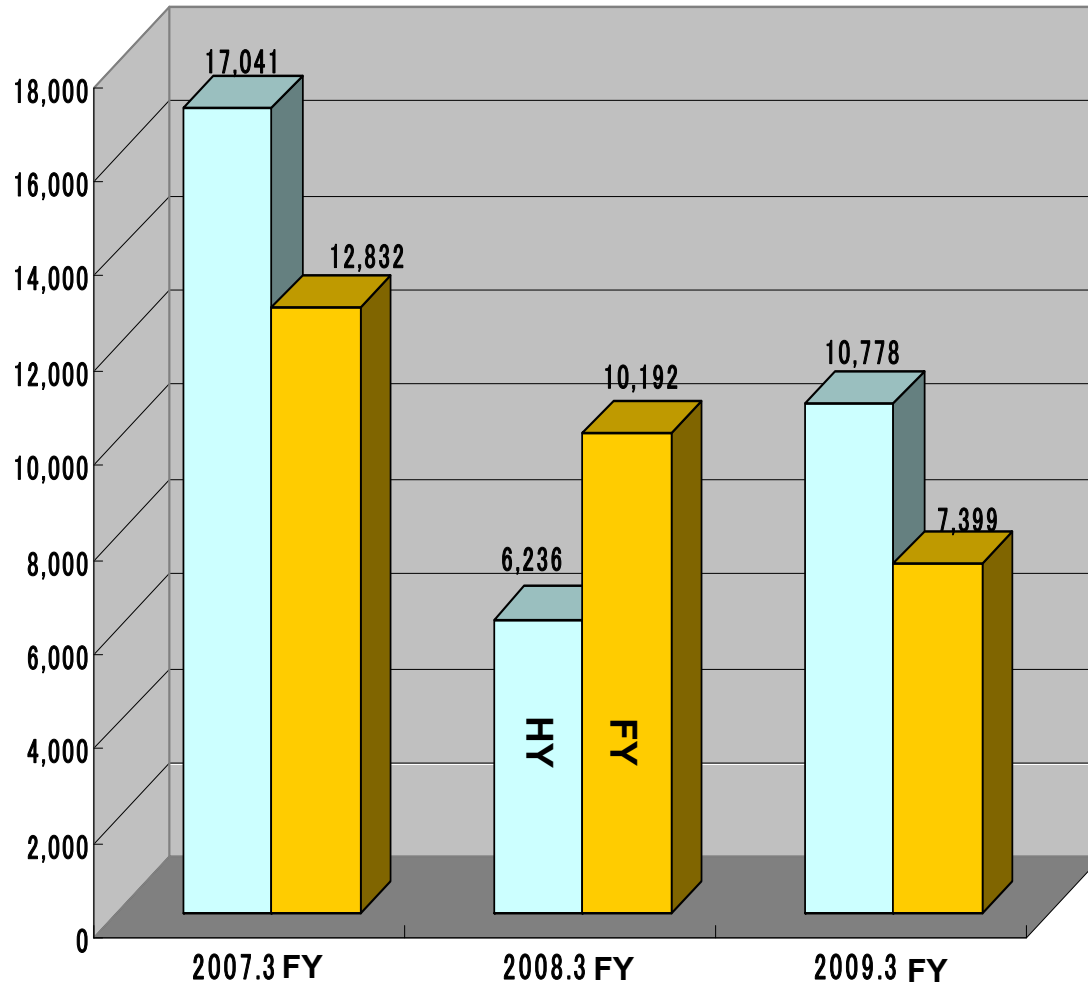
Business Units	2007 FY	2008 FY	2009 FY	Change from last FY	Change from last FY(%)
Memory Disk	2,795	862	291	▲571	▲66.2%
Plasma System	9,878	8,928	7,097	▲1,831	▲20.5%
Semiconductor	157	401	10	▲391	▲97.5%
FEL	—	—	0	—	—
Total	12,832	10,192	7,399	▲2,793	▲27.4%



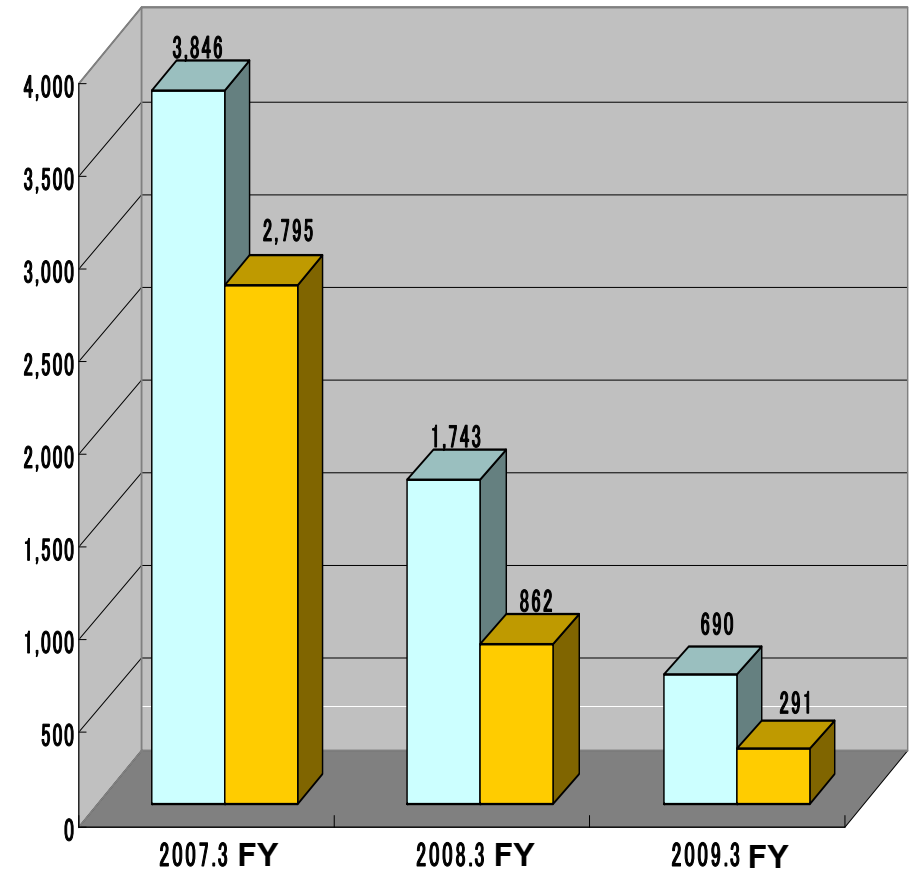
2-4 Backlog Orders by Business Unit (Consolidated)

(Million¥)

Total Backlog Orders



Memory Disk Backlog Orders

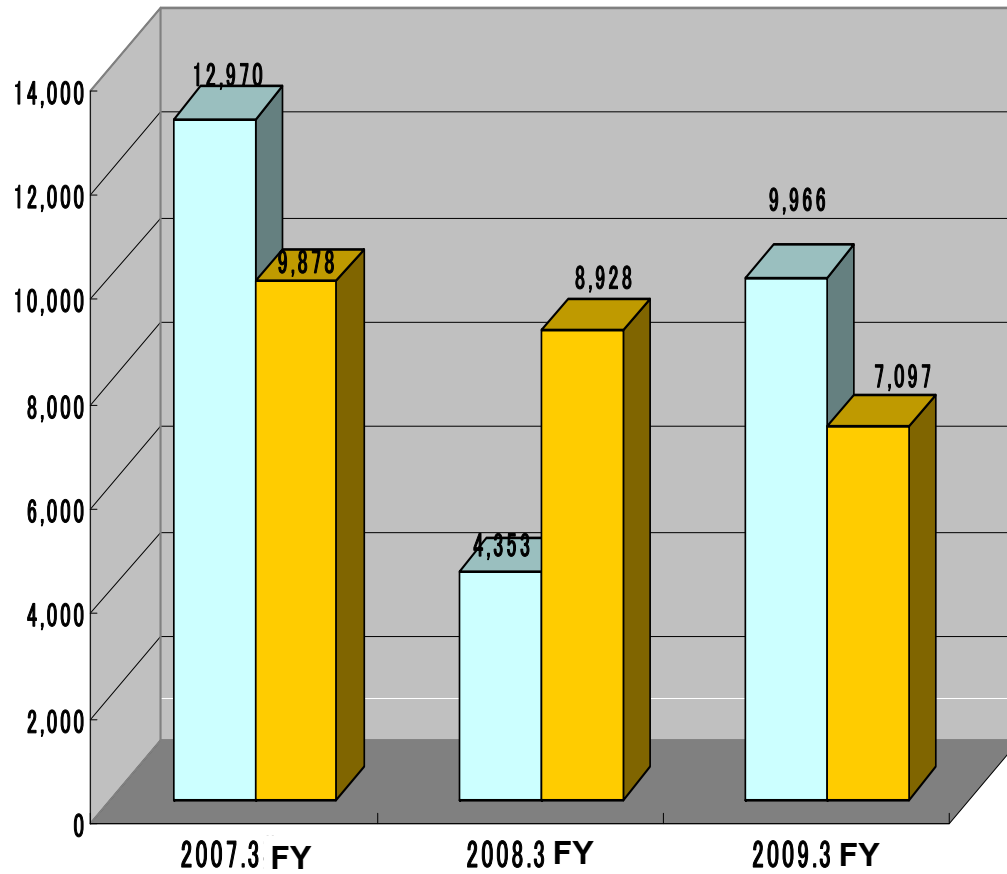




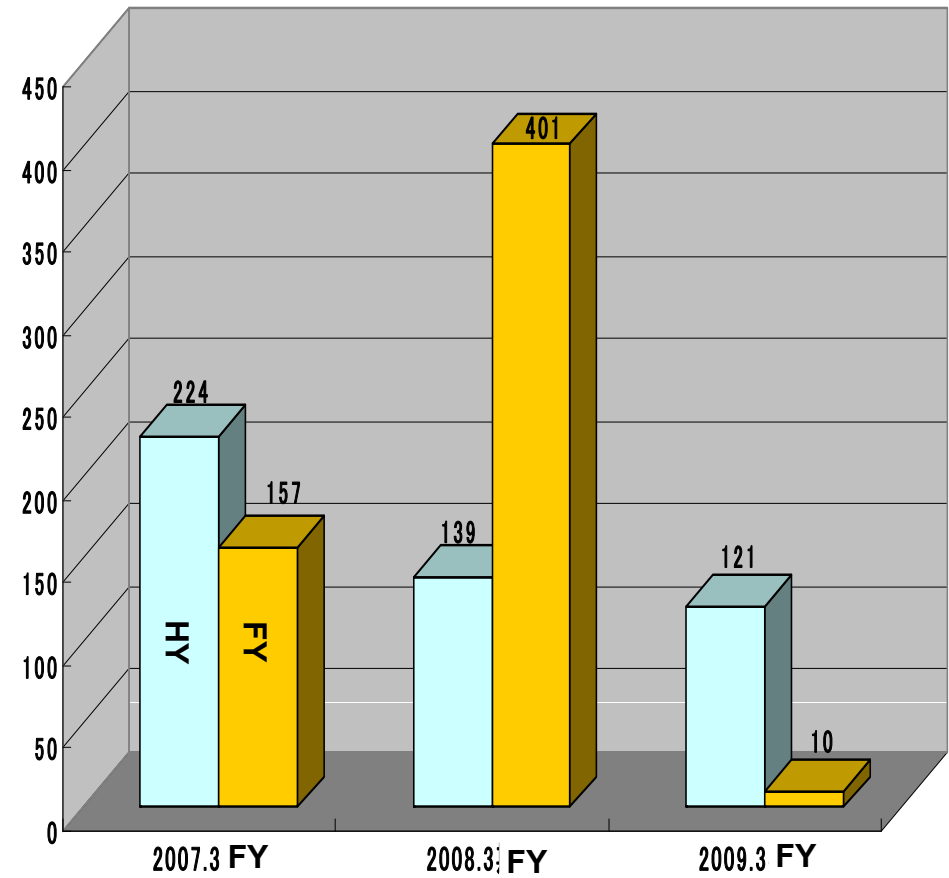
2-4 Backlog Orders by Business Unit (Consolidated)

(Million¥)

Plasma System



Semiconductor





2-5 Summary of Profit & Loss (Consolidated)

(Million¥)

Items	2007 FY	2008 FY	2009 FY	Change from last FY	Change from last FY(%)
Net Sales	22,423	21,197	12,628	▲8,569	▲40.4%
Cost of Sales	16,710	16,693	10,224	▲6,469	▲38.8%
Gross Profit	5,712	4,503	2,403	▲2,100	▲46.6%
Sales & Administrative expenses	2,036	2,208	2,147	▲61	▲2.8%
Operating income	3,676	2,295	255	▲2,040	▲88.9%
Non Operating Income	73	169	243	74	43.8%
Non Operating Expenses	166	92	69	▲23	▲25.0%
Ordinary Income	3,583	2,371	430	▲1,941	▲81.9%
Extraordinary Gain	8	6	10	4	66.7%
Extraordinary Loss	117	3	28	25	833.3%
Income before Tax	3,474	2,374	412	▲1,962	▲82.6%
Income Tax	1,371	850	▲97	▲947	—
Net Income	2,103	1,524	510	▲1,014	▲66.5%



2-6 Summary of Balance Sheet (Consolidated)

(Million¥)

Items	2007 FY	2008 FY	2009 FY	Change from last FY	Change from last FY(%)
Current Assets	20,637	18,235	13,607	▲4,628	▲25.4%
Cash & cash equivalents	5,359	4,625	5,351	726	15.7%
Account receivables	7,470	9,217	4,647	▲4,570	▲49.6%
Inventories	7,203	4,152	2,994	▲1,158	▲27.9%
Others	603	240	613	374	155.8%
Fixed Assets	2,969	3,165	3,357	192	6.1%
Tangible fixed assets	2660	2,827	2,842	15	0.5%
Intangible fixed assets	109	99	88	▲11	▲11.1%
Investments and others	199	238	426	188	79.0%
Total Assets	23,607	21,401	16,965	▲4,436	▲20.7%
Current liabilities	12,465	8,499	3,513	▲4,986	▲58.7%
Accounts payables	9,199	4,133	2,443	▲1,690	▲40.9%
Short-term liabilities	1,363	3,646	611	▲3,035	▲83.2%
Short-term liabilities	1,902	719	459	▲260	▲36.2%
Fixed liabilities	1,097	2,172	2,654	482	22.2%
Long-term liabilities	609	1,621	2,128	507	31.3%
Others	488	550	525	▲25	▲4.5%
Total liabilities	13,563	10,672	6,167	▲4,505	▲42.2%
Total Net Assets	10,044	10,729	10,797	68	0.6%
Total Liabilities & Net Assets	23,607	21,401	16,965	▲4,436	▲20.7%



2-7 Summary of Cash Flow Statement (Consolidated)

(Million¥)

Items	2007 FY	2008 FY	2009 FY
Cash Flow from operating activities	2,095	▲2,823	3,568
Cash Flow from Investing activities	▲91	▲306	▲11
Cash Flow from financing activities	▲1,400	2,582	▲2,814
Cash and cash equivalents at the end of the period	5,335	4,621	5,344



3. Business planning for year 2009.

(The 10th medium term of planning out line.)



3-1 Basic Strategy of 10th. Mid-Term Plan

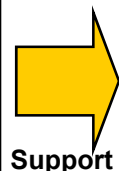
The 10th medium term of plan (Year of 2009 to 2011)

2009. April 1st

Constructing high earnings of corporate culture and aim expand business.

(Back-up the constructing high earnings of corporate culture and aim expand business.)

Material Head quarter
 Management Head quarter
 Management planning Office
 Internal audit office
 Environmental management office



Accomplishment for business budget

Division

- Memory disk
- Semiconductor
- Plasma system
- Cleaning
- FEL
- Solar battery

Subsidiary company

- HYAC
- YSS
- YNS

Investing company

- ND Materials
- Shinoda Plasma

(1) Fundamental business policy

- Constructing high earnings of corporate culture
- Expand business
- Urgent magnify the device business
- Global management
- Cleaning new deal
- Strengthen internal organization
- Worthwhile management

(2) Management target

- Gross sales over 50 billion yen
- Sales profit rate over 15%
- New product sales over 20%

(3) Business strategy for attain management target

Existing Division

- Share-up Main products (Differentiated)
- Increase sales products (Alliance)
- Expand global business (South east Asia)
- Magnify service bushiness
- Commitment system
- Division cost reduction
- Low cost Management
- Personnel training
- Motivation

Development work

- Speed-up for R&D
- Alliance

Business growing by M&A

- Participate new business
- Synergy effect



3-2 Guidelines for business activities year 2009

- 1) Surrounding business circumference to our company.**
- 2) Key word of year 2009**
- 3) Reinforce for business structure**
- 4) Challenge for more growing**



3-3 Year 2009 important measures

[1] Challenge to be a High Profit Company (structuring the company policy)

- 1) Sales strategy**
- 2) Division cost reduction (Gross margin up)**
- 3) Low cost management (Fixed expenses reduction)**
- 4) Sheared intelligence (Highly motivation)**

[2] Expand business scale

- 1) Previous business**
- 2) New business**

[3] Environmental management

[4] Others



3-4 Plan for whole FY 2009 (consolidated)

(Million¥)

Items	2007 FY	2008 FY	2009 FY	2010 March (Forecast)		Change from last FY (Forecast)	Change from last FY(%) (Forecast)
				2 nd half (Forecast)	Year (Forecast)		
Net Sales	22,423	21,197	12,628	2,500	11,000	▲1,628	▲12.9%
Operation Income	3,676	2,295	255	▲400	300	45	17.6%
Ordinary Income	3,583	2,371	430	▲420	250	▲180	▲41.9%
Net Income	2,103	1,524	510	▲420	150	▲360	▲70.6%
Earning/Share (Yen)	219.1	158.1	54.8	—	16.1	▲38.7	▲70.6%



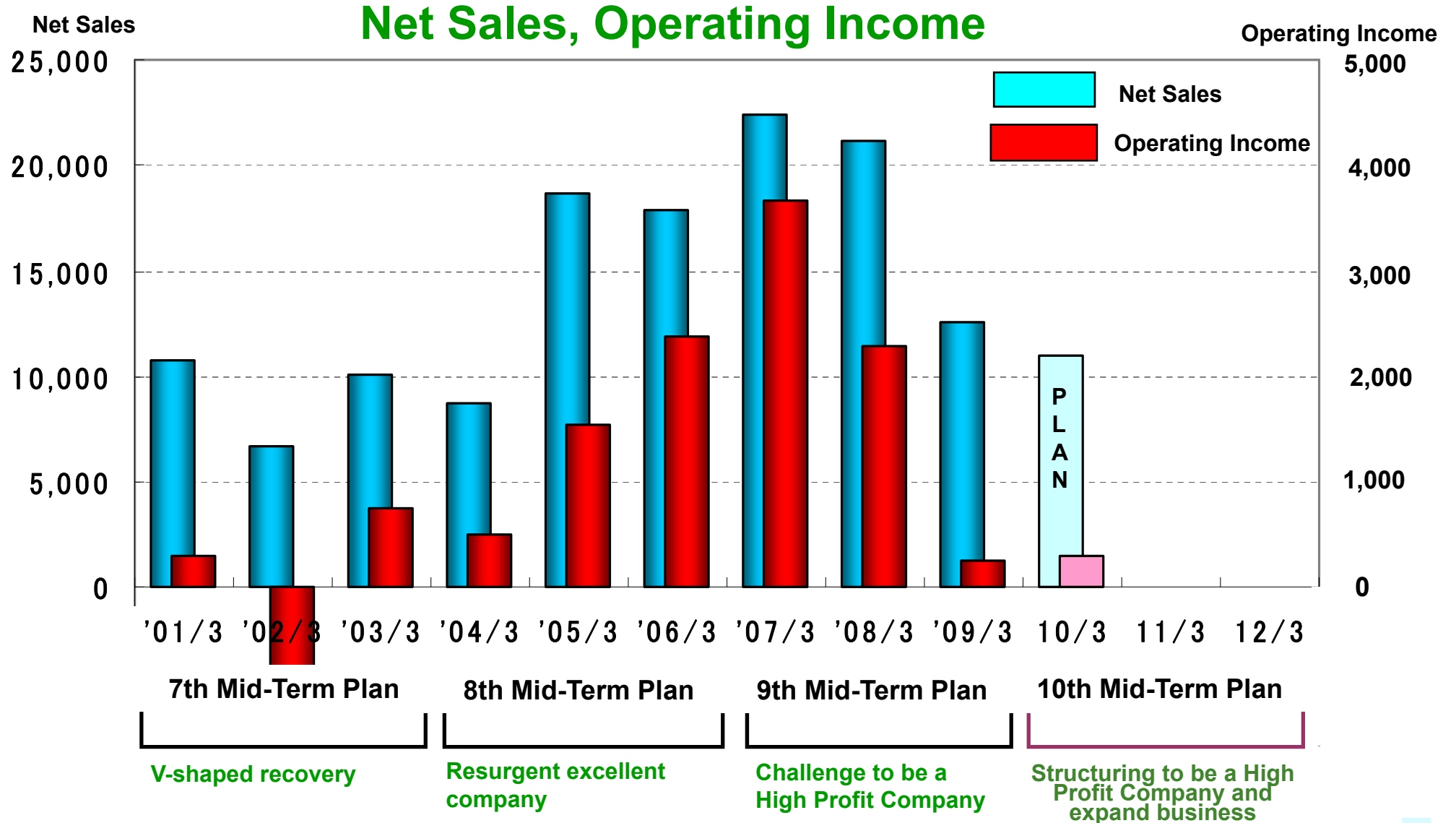
3-4 Sales Forecast by Business Unit (consolidated) (Million¥)

Business Segment	2007 FY	2008 FY	2009 FY	2010 March (Forecast)		Change from last FY (Forecast)	Change from last FY(%) (Forecast)
				2 nd half (Forecast)	Year (Forecast)		
Memory Disk	9,899	7,039	2,238	700	2,300	62	2.8%
Plasma system	9,400	10,919	7,609	820	5,000	▲2,609	▲34.3%
Semiconductor	1,403	1,093	1,164	200	700	▲464	39.9%
FEL	—	—	1	0	10	9	900.0%
Solar battery	—	—	—	45	1,300	—	—
Cleaning	1,720	2,145	1,615	735	1,690	75	4.6%
Total	22,423	21,197	12,628	2,500	11,000	▲1,628	▲12.9%



3-5 Business performance transition & 10th Mid-Term Plan Consolidated

(Million¥)





<<Caution>>

The prospects described in this document is based on the information we have as of the time this document is published, and the actual result may differ from such prospects due to various unexpected factors.

Y. A. C. Co.,